

ABSTRACT

MOLD CONDITIONING RESIN COMPOSITION AND METHOD OF MOLD CONDITIONING

The mold conditioning resin composition of the present invention is used in molding a curing resin molding compound to impart release properties to a mold surface after stains have been removed therefrom. The resin composition contains a melamine resin, at least one kind of a metal soap-based release agent, and a fatty acid ester-based release agent and/or a synthetic wax. The mold conditioning resin composition of the present invention exhibits superior restoration of mold release properties, which lasts for a long period of time and enables a long-lasting consecutive molding of encapsulation molded articles.